

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"5706578".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/02/10 20:40
S1	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/23 20:33
S2	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 20:34
S3	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 20:39
S4	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 20:48
S5	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 20:48

S12	1094	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 14:31
S13	123	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 20:41
S14	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 14:36
S15	3	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 14:37
S16	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 14:38
S17	2	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 16:16
S18	190	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 16:16
S19	135	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 16:17
S20	68	interconnect near3 copper with transistor	USPAT	OR	ON	2005/07/24 16:40
S21	1	"4939568".pn.	USPAT	OR	ON	2005/07/24 16:41

S22	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 20:40
S23	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
S24	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
S25	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
S26	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
S27	61	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 20:41

S28	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:57
S29	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S30	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S31	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S32	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S33	1144	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:57
S34	125	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:57
S35	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57

S36	3	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S37	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S38	2	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:57
S39	202	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:57
S40	144	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:57
S41	69	interconnect near3 copper with transistor	USPAT	OR	ON	2005/12/12 21:57
S42	1	"4939568".pn.	USPAT	OR	ON	2005/12/12 21:57
S43	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S44	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:57

S45	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S46	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S47	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:57
S48	62	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:57
S49	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:57
S50	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S51	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44

S52	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S53	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S54	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S55	1146	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S56	125	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S57	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S58	3	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S59	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S60	2	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S61	202	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S62	144	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44

S63	69	interconnect near3 copper with transistor	USPAT	OR	ON	2005/12/15 15:44
S64	1	"4939568".pn.	USPAT	OR	ON	2005/12/15 15:44
S65	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S66	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S67	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S68	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S69	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S70	62	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44

S71	1146	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S72	202	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S73	62	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S74	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S75	1	"4939568".pn.	USPAT	OR	ON	2005/12/15 15:44
S76	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S77	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S78	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S79	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44

S80	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S81	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S82	3	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S83	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S84	2	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S85	69	interconnect near3 copper with transistor	USPAT	OR	ON	2005/12/15 15:44
S86	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S87	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44

S88	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S89	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/15 15:44
S90	125	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S91	144	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S92	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 15:44
S93	2	"6677619".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:21
S94	144	andujar.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:21
S95	10	("3904442" "4275410" "4612083" "4760335" "4761681" "5386142" "5474458" "5528080" "5608264" "5973368").PN. OR ("6661086").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:22

S96	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S97	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S98	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S99	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S100	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S101	1263	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S102	132	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S103	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40

S104	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S105	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S106	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S107	246	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S108	171	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S109	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/02 14:40
S110	1	"4939568".pn.	USPAT	OR	ON	2006/08/02 14:40
S111	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S112	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40

S113	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S114	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S115	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S116	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S117	1263	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S118	246	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S119	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S120	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S121	1	"4939568".pn.	USPAT	OR	ON	2006/08/02 14:40
S122	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40

S123	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S124	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S125	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S126	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S127	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S128	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S129	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S130	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40

S131	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/02 14:40
S132	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S133	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S134	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S135	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S136	132	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S137	171	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40

S138	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S139	1263	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S140	246	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S141	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S142	1263	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S143	246	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S144	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S145	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S146	1	"4939568".pn.	USPAT	OR	ON	2006/08/02 14:40
S147	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S148	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S149	1	"4939568".pn.	USPAT	OR	ON	2006/08/02 14:40
S150	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40

S151	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S152	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S153	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S154	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S155	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S156	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S157	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S158	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40

S159	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/02 14:40
S160	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S161	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S162	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S163	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S164	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40

		"5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.				
S165	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S166	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S167	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S168	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S169	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S170	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S171	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S172	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/02 14:40

S173	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S174	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S175	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S176	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 14:40
S177	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S178	132	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S179	171	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40

S180	132	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S181	171	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 14:40
S182	45	("4675717" "5270261" "5419806" "5426072" "5496743"). PN. OR ("5902118"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/02 16:12
S183	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S184	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S185	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S186	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S187	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S188	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S189	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S190	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S191	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S192	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S193	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S194	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S195	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S196	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
S197	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
S198	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S199	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S200	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S201	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S202	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S203	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S204	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S205	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

S206	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S207	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S208	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
S209	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S210	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S211	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S212	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S213	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S214	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S215	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S216	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S217	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S218	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
S219	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S220	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S221	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S222	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S223	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S224	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S225	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S226	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S227	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S228	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S229	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S230	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S231	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S232	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S233	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
S234	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S235	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S236	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
S237	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S238	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S239	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S240	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S241	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S242	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S243	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S244	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S245	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S246	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
S247	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S248	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S249	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S250	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S251	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S252	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S253	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S254	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S255	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S256	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S257	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S258	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

S259	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
S260	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S261	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S262	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S263	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S264	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S265	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

S266	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S267	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S268	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S269	144	andujar.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S270	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S271	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S272	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S273	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S274	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S275	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S276	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S277	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S278	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S279	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S280	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S281	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
S282	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S283	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S284	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S285	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S286	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S287	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S288	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

		"5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.				
S289	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S290	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S291	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S292	10	("3904442" "4275410" "4612083" "4760335" "4761681" "5386142" "5474458" "5528080" "5608264" "5973368").PN. OR ("6661086").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S293	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S294	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S295	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S296	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31

S297	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S298	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S299	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S300	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S301	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S302	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S303	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S304	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
S305	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:31
S306	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S307	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S308	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31

S309	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S310	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S311	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:31
S312	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:31
S313	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S314	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S315	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:31
S316	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32

S317	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S318	66	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S319	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S320	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S321	1264	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S322	247	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S323	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S324	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:32
S325	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:32
S326	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S327	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S328	1	"4939568".pn.	USPAT	OR	ON	2006/08/03 09:32
S329	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32

S330	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S331	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S332	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S333	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S334	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S335	3	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S336	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S337	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32

S338	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S339	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S340	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S341	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S342	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S343	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32

		"5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.				
S344	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S345	92	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S346	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S347	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S348	5	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S349	81	interconnect near3 copper with transistor	USPAT	OR	ON	2006/08/03 09:32
S350	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32

		"6441478" "6717244" "0077467").PN.				
S351	10	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S352	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S353	2	("5940683").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S354	133	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S355	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S356	172	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32
S357	45	("4675717" "5270261" "5419806" "5426072" "5496743"). PN. OR ("5902118"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 09:32
S358	2	"6677619".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 09:32

S359	24	("20010029087" "20020081821" "20060099796" "20080064183" "6436794" "64444493" "6593213" "6621169" "6881647" "7067909" "7078811" "7189632"). PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/21 16:24
S360	14	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/05/21 17:33

2/10/2010 9:01:56 PM

C:\Documents and Settings\landujar\My Documents\EAST\Workspaces\% 10655854.wsp